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(12) **United States Design Patent**  
**Fukushima et al.**

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(54) **ELASTIC MEMBRANE FOR SEMICONDUCTOR WAFER POLISHING**

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See application file for complete search history.

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(57) **CLAIM**

The ornamental design for an elastic membrane for semiconductor wafer polishing, as shown and described.

**DESCRIPTION**

FIG. 1 is a front view of an elastic membrane for semiconductor wafer polishing showing our new design;  
FIG. 2 is a rear view thereof;  
FIG. 3 is a plain view thereof;  
FIG. 4 is a bottom view thereof;  
FIG. 5 is a right side view thereof;  
FIG. 6 is a left side view thereof;  
FIG. 7 is a cross section view taken along the line 7-7 of FIG. 2 thereof;  
FIG. 8 is an enlarged view of part 8 of FIG. 7 thereof; and,  
FIG. 9 is an enlarged view taken of portion 9-9' of FIG. 8 thereof.

The broken lines depict environmental subject matter only and form no part of the claimed design.

**1 Claim, 3 Drawing Sheets**



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FIG. 1

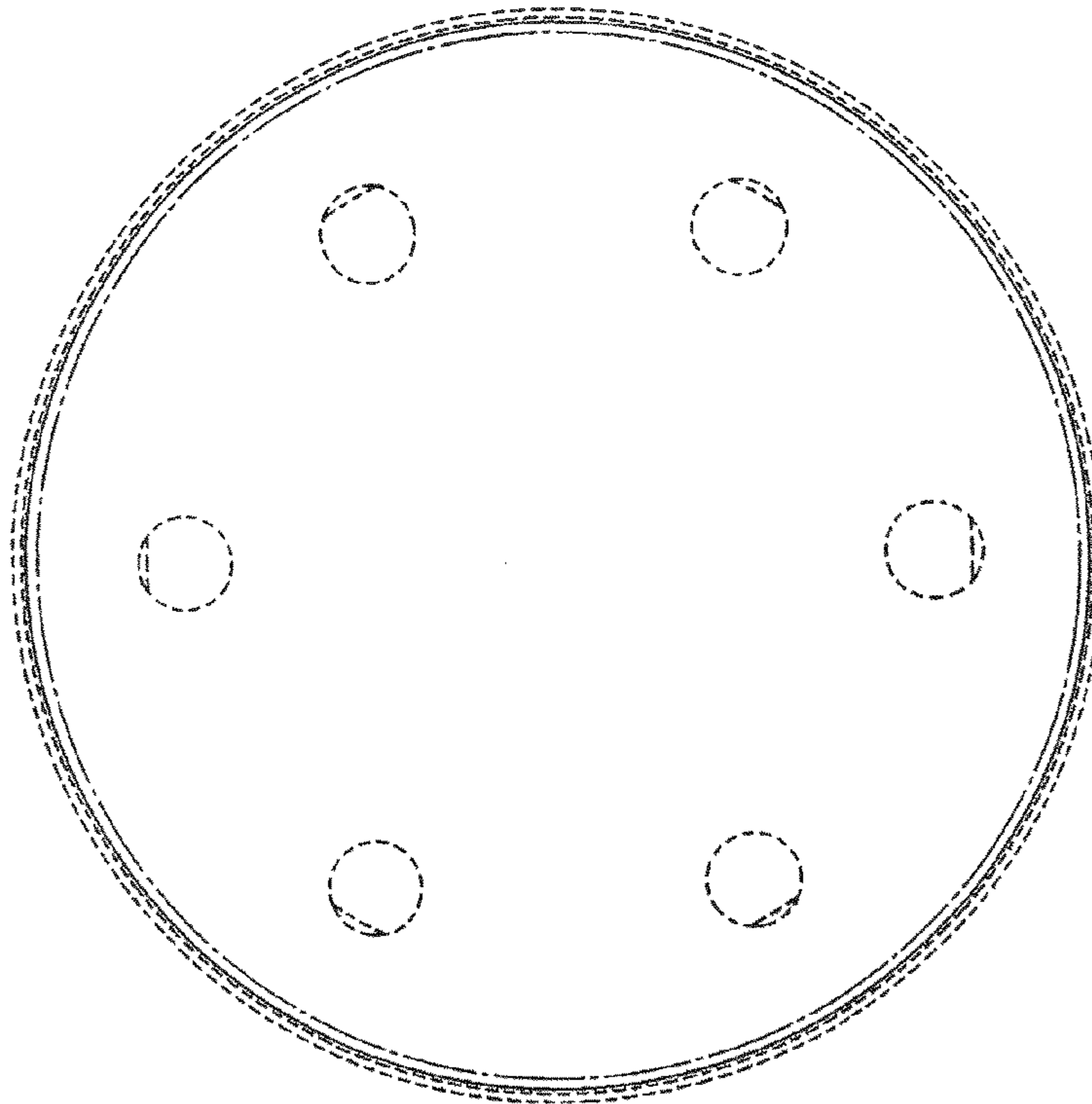


FIG. 2

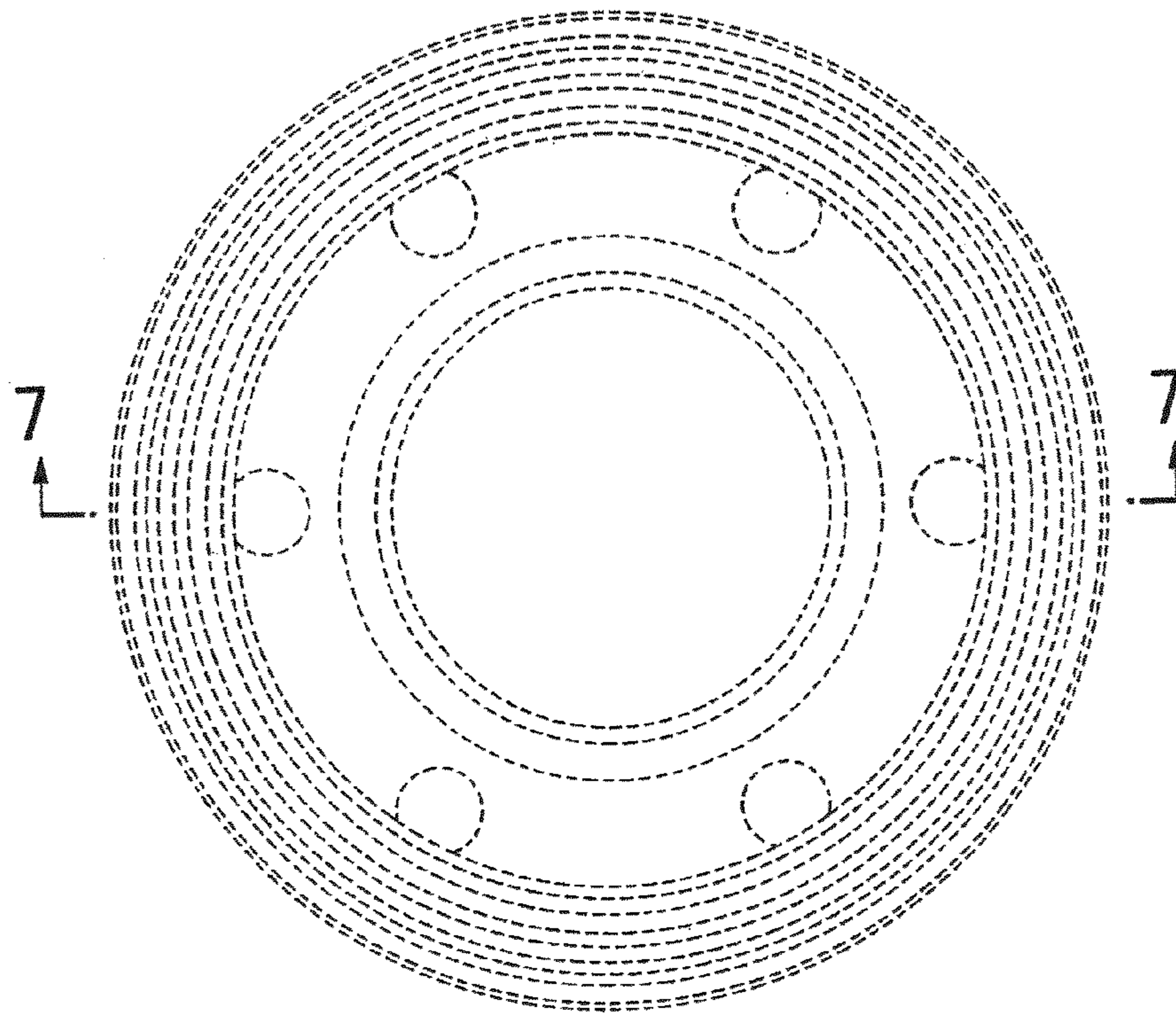


FIG. 3

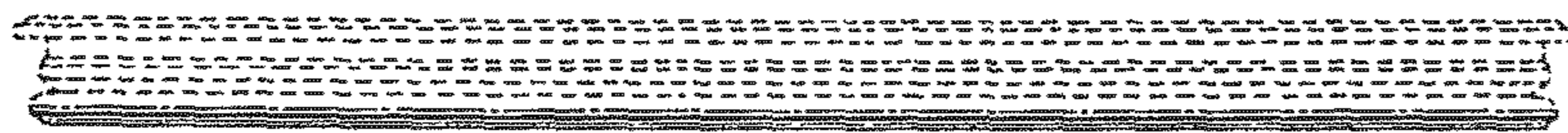


FIG. 4



FIG. 5



FIG. 6



FIG. 7

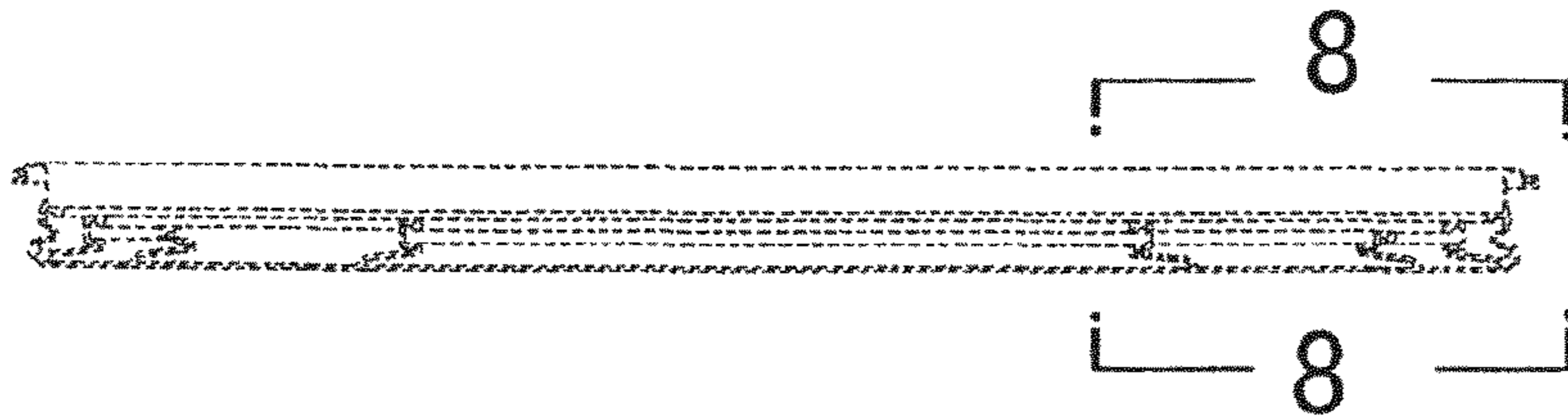


FIG. 8

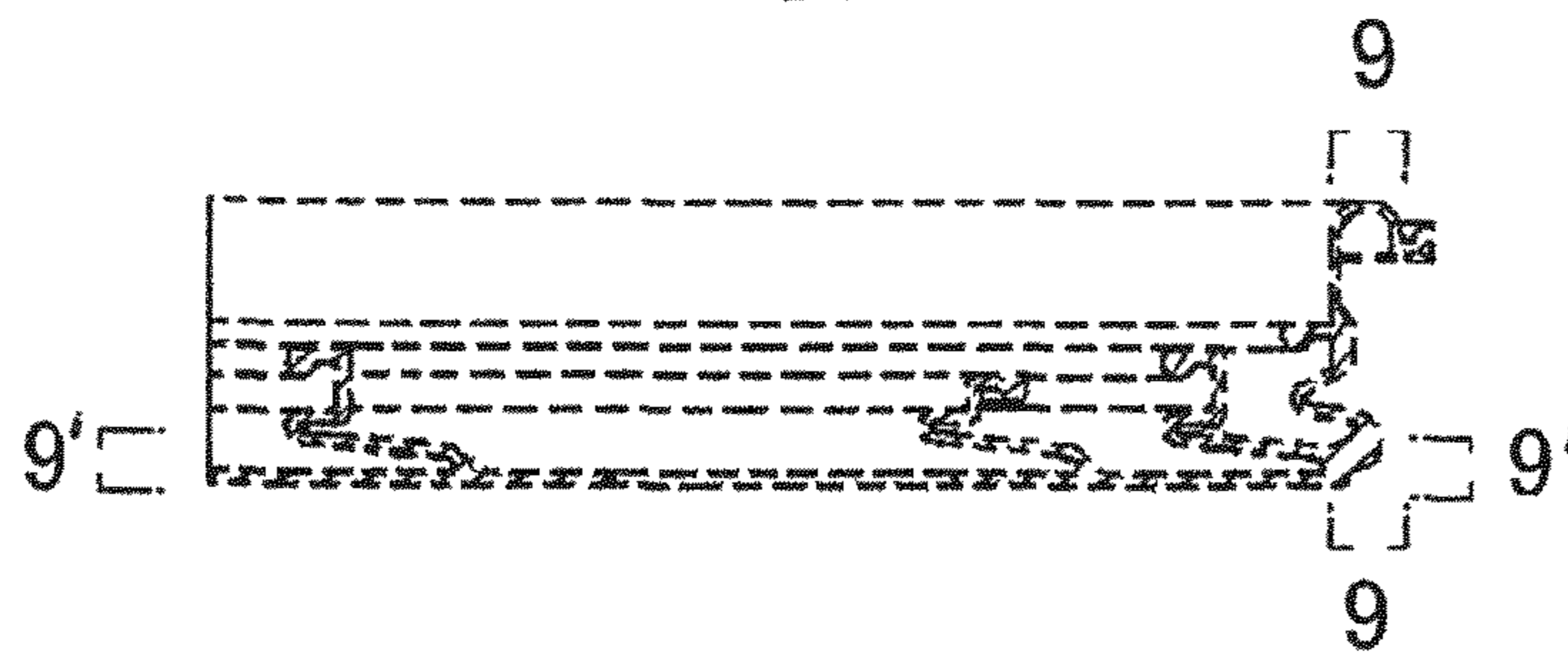


FIG. 9

